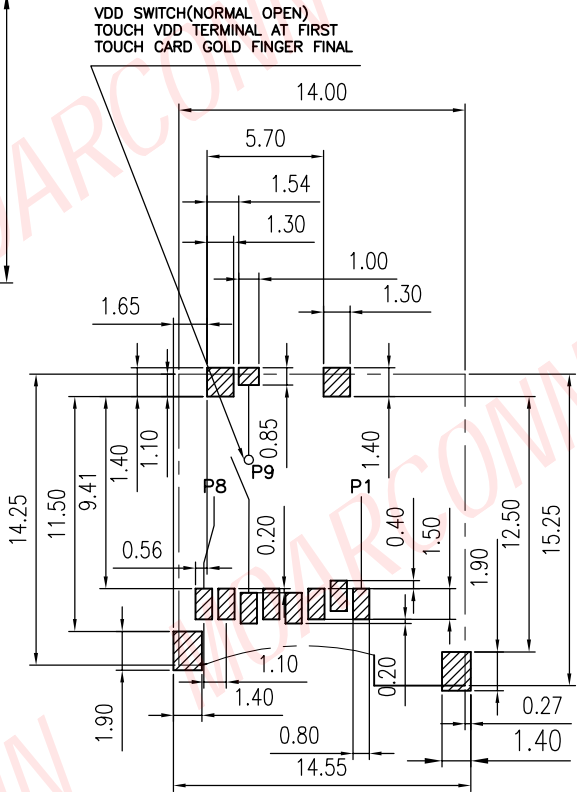
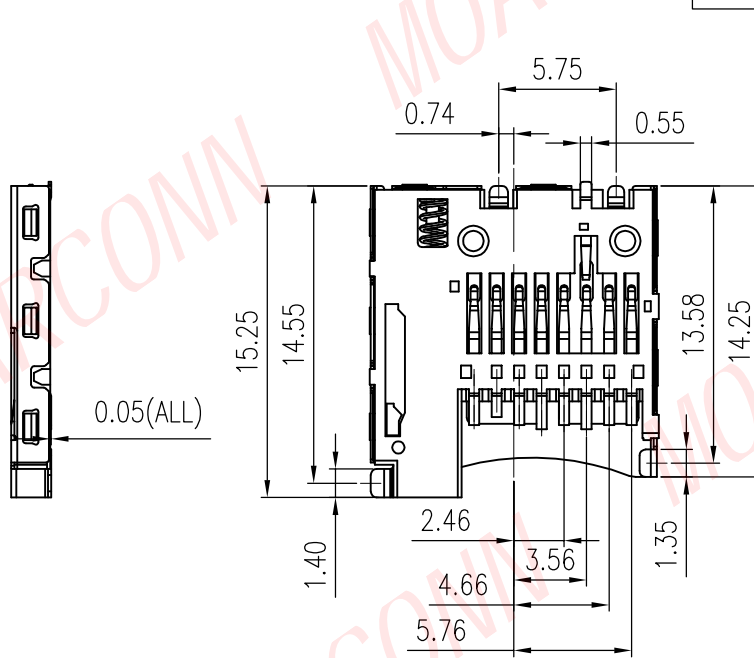
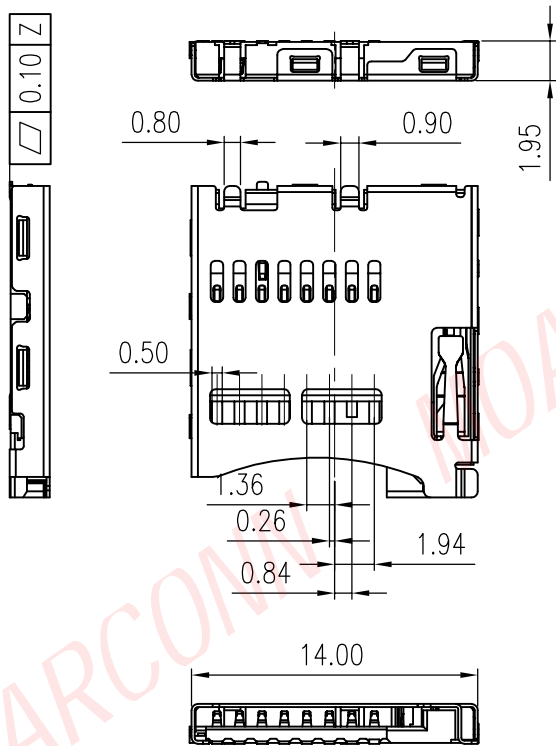
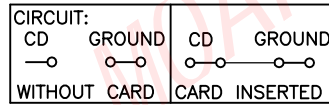


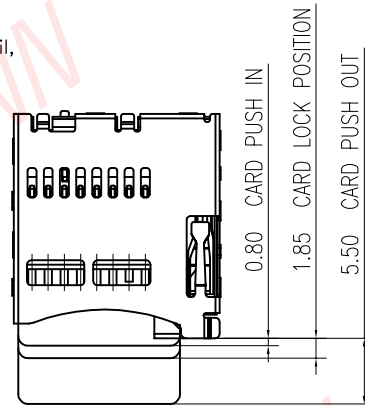
All materials, plating and process meet HF requirements.



Switch Condition



Pin No.	MICRO SD	
PIN1	DAT2	1P
PIN2	CD/DAT3	2P
PIN3	CMD	3P
PIN4	VDD	4P
PIN5	CLK	5P
PIN6	VSS	6P
PIN7	DAT0	7P
PIN8	DAT1	8P
PIN9	CARD DETECT	



NOTES:

1. MATERIAL:

Housing: High Temperature Thermoplastic UL94V-0; Color Black.

Contacts: Phosphor Bronze.

Au G/F, Under plate Ni 40u"Min all over at Solder Tail,

Selected Gold Flash on Contact Area plating.

Shell: Stainless.

Gold Flash on Contact solder Area Over Nickel Plating.

2. Electrical Characteristics:

Operating voltage :10v AC(rms)/DC.

Current rating :0.5 A.

Operating Temperature: -25°C~+85°C.

Insulation resistance: 1000M ohms min. at 500VDC

Dielectric withstanding voltage :500 VAC/1minute.

Contact resistance: 100m ohms max.

3. Mechanical characteristics

Insertion force: 40N Max.

Extraction force: 0.5N Min.

Mating durability: 10000 cycles at the speed rate of 400-600 cycles/h; Without distortion of plastic and serious wear and tear in terminal, No signal break.

RECOMMEND PCB LAYOUT
GENERAL TOLERANCE ±0.05

MOARCONN
MORE CONNECTIONS. SMARTER FUTURE.

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

DIMENSIONS INIT: mm

UNLESS OTHERWISE SPECIFIABLE

DIMENSION TOLERANCE

X.X: ± 0.35

X.XX: ± 0.25

X.XXX: ± 0.10

ANGULAR: ± 2'

PRODUCT NAME : MICRO SD P-P H1.95 内焊无柱
DRAWING: Seven
DATE: 2024.03.08

PRODUCT NO. : MC195-T1251-01-W
CHECK: DATE:

DRAWING NO. : D-MC195-T1251-01-W
APPROVED: DATE:

SCALE: 1:1
DWG ID: C D
REV.: B
PAGE: 1 of 1

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
B	----	The welding feet plating of terminals are changed from tin to gold.	Seven	2024.03.08

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